

**HIGH NOISE REDUCTION, HIGH-SPEED 10 Mbps
TOTEM POLE OUTPUT TYPE
8-PIN DIP PHOTOCOUPLER**

–NEPOC Series–

DESCRIPTION

The PS9611 and PS9611L are optically coupled high-speed, totem pole output isolators containing a GaAlAs LED on the input side and a photodiode and a signal processing circuit on the output side on one chip.

The PS9611 is in a plastic DIP (Dual In-line Package) and the PS9611L is lead bending type (Gull-wing) for surface mounting.

FEATURES

- High common mode transient immunity ($CM_H, CM_L = \pm 10 \text{ kV}/\mu\text{s}$ TYP.)
- High-speed response ($t_{PHL} = 30 \text{ ns}$ TYP., $t_{PLH} = 35 \text{ ns}$ TYP.)
- Pulse width distortion ($|t_{PHL} - t_{PLH}| = 5 \text{ ns}$ TYP.)
- Totem pole output (No pull-up resistor required)
- Ordering number of tape product: PS9611L-E3, E4: 1 000 pcs/reel
- Safety standards
 - UL approved: File No. E72422 (S)
 - VDE0884 approved (Option) : No.91877

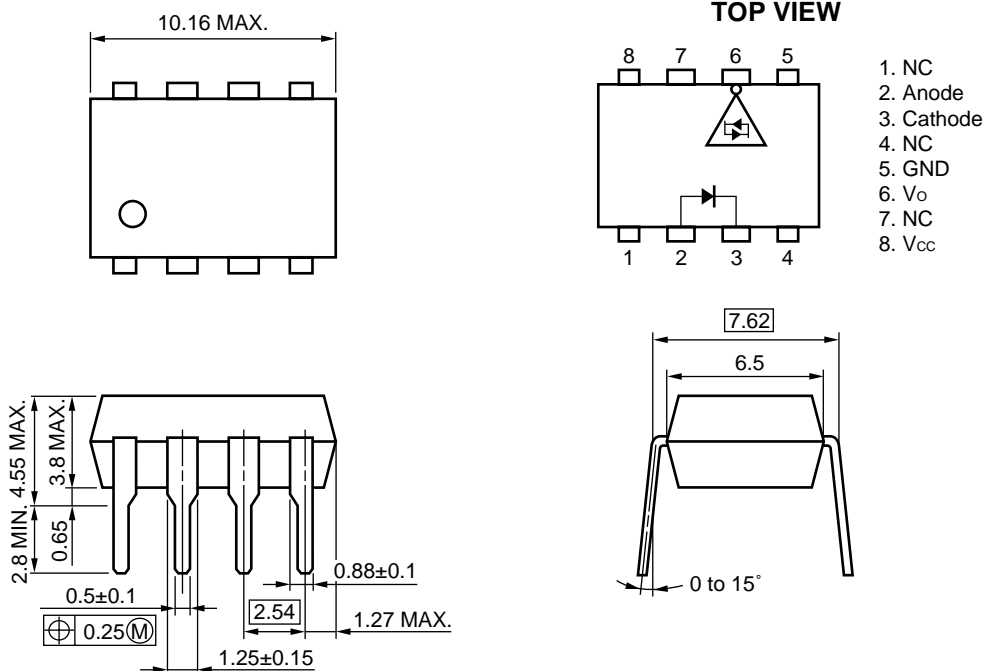
APPLICATIONS

- Computer and peripheral manufactures
- Measurement equipment
- PDP

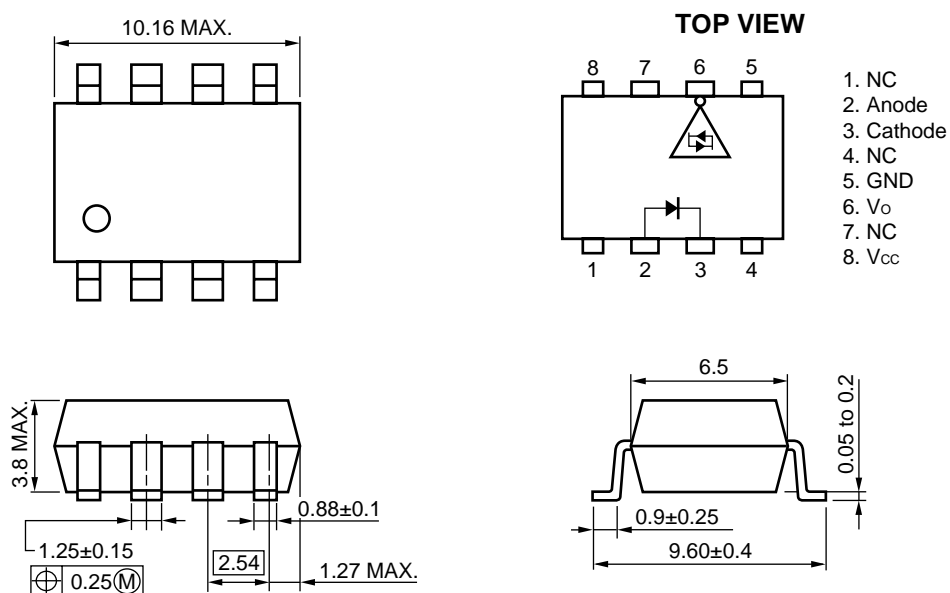
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PACKAGE DIMENSIONS (UNIT: mm)

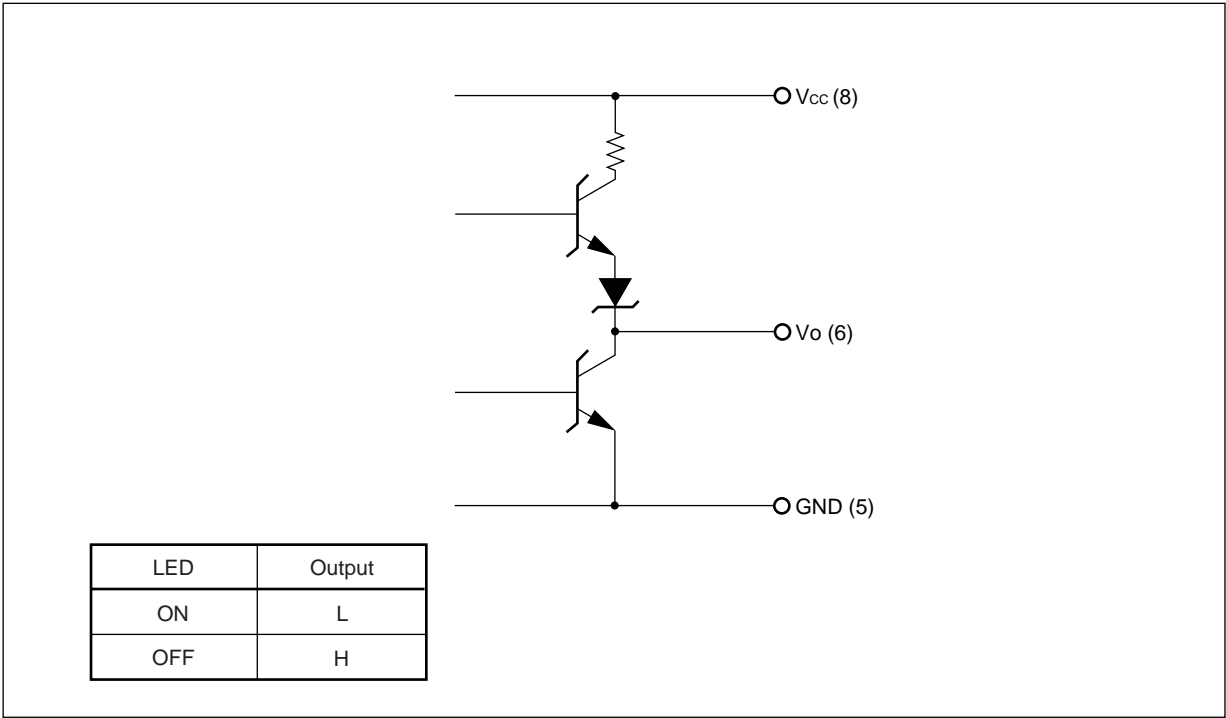
PS9611



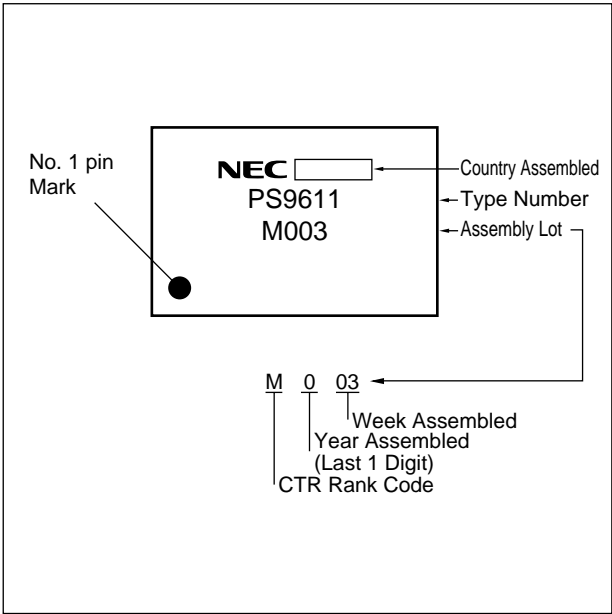
PS9611L



INTERNAL OUTPUT CIRCUIT



MARKING EXAMPLE



ORDERING INFORMATION

Part Number	Package	Packing Style	Safety Standards Approval	Application Part Number ^{*1}	
PS9611	8-pin DIP	Magazine case 50 pcs	Approved products other than VDE	PS9611	
PS9611L				PS9611L	
PS9611L-E3		Embossed Tape 1 000 pcs/reel			
PS9611L-E4					
PS9611-V		Magazine case 50 pcs	VDE0884 approved (Option)	PS9611	
PS9611L-V				PS9611L	
PS9611L-V-E3		Embossed Tape 1 000 pcs/reel			
PS9611L-V-E4					

*1 For the application of the Safety Standard, following part number should be used.

ABSOLUTE MAXIMUM RATINGS (T_A = 25°C, unless otherwise specified)

Parameter		Symbol	Ratings	Unit
Diode	Forward Current	I _F	30	mA
	Reverse Voltage	V _R	3.0	V
Detector	Supply Voltage	V _{CC}	7	V
	Output Voltage	V _O	7	V
	High Level Output Current ^{*1}	I _{OH}	−5	mA
	Low Level Output Current ^{*1}	I _{OL}	25	mA
	Power Dissipation ^{*1,2}	P _C	150	mW
Isolation Voltage ^{*3}		BV	3 750	Vr.m.s.
Operating Ambient Temperature		T _A	−40 to +85	°C
Storage Temperature		T _{stg}	−55 to +125	°C

*1 T_A = −40 to +85°C

*2 Applies to output pin V_O and power supply pin V_{CC}.

*3 AC voltage for 1 minute at T_A = 25°C, RH = 60% between input and output.

RECOMMENDED OPERATING CONDITIONS

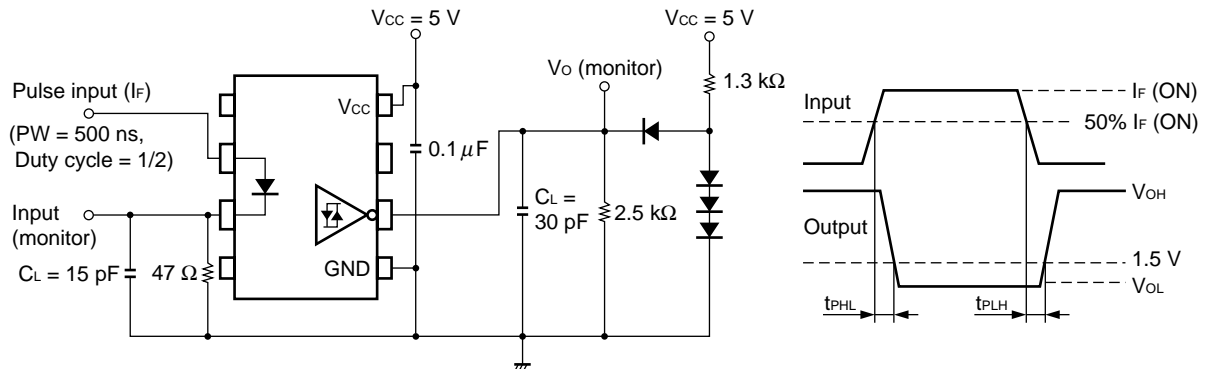
Parameter	Symbol	MIN.	TYP.	MAX.	Unit
High Level Input Current	I _{FH}	7.5		12.5	mA
Low Level Input Current	I _{FL}	0		250	μA
Supply Voltage	V _{CC}	4.5	5.0	5.5	V
TTL (loads)	N			5	

ELECTRICAL CHARACTERISTICS ($T_A = -40$ to $+85^\circ\text{C}$, unless otherwise specified)

Parameter		Symbol	Conditions	MIN.	TYP. ¹⁾	MAX.	Unit	
Diode	Forward Voltage	V _F	I _F = 10 mA, T _A = 25°C	1.4	1.65	1.9	V	
	Reverse Current	I _R	V _R = 3 V, T _A = 25°C			10	μA	
	Terminal Capacitance	C _t	V = 0 V, f = 1 MHz, T _A = 25°C		30		pF	
Detector	High Level Output Current	I _{OH}	V _{CC} = V _O = 5.5 V, I _F = 250 μA		1	200	μA	
	High Level Output Voltage	V _{OH}	V _{CC} = 4.5 V, I _F = 250 μA, I _{OH} = −2 mA	2.4	3.0		V	
	Low Level Output Voltage	V _{OL}	V _{CC} = 4.5 V, I _F = 7 mA, I _{OL} = 8 mA		0.38	0.6	V	
	High Level Supply Current	I _{CCH}	V _{CC} = 5.5 V, I _F = 0 mA		11	17	mA	
	Low Level Supply Current	I _{CCL}	V _{CC} = 5.5 V, I _F = 10 mA		12	18	mA	
	High Level Output Short Circuit Current	I _{OSH}	V _{CC} = 5.5 V, V _O = GND, I _F = 0 mA, 10 ms or less		−26		mA	
	Low Level Output Short Circuit Current	I _{OSL}	V _{CC} = V _O = 5.5 V, I _F = 8 mA, 10 ms or less		34		mA	
Coupled	Threshold Input Current (H → L)	I _{FHL}	V _{CC} = 5 V	T _A = 25°C		2.7	5	mA
							6	
	Threshold Input Current (L → H)	I _{FLH}	V _{CC} = 5 V	T _A = 25°C	0.5			mA
					0.35			
	Isolation Resistance	R _{I-O}	V _{I-O} = 1 kV _{DC} , R _H = 40 to 60%, T _A = 25°C		10 ¹¹			Ω
	Isolation Capacitance	C _{I-O}	V = 0 V, f = 1 MHz, T _A = 25°C			0.9		pF
	Propagation Delay Time (H → L) ²	t _{PHL}		T _A = 25°C	15	30	65	ns
			V _{CC} = 5 V, I _F = 7.5 mA		10		85	
	Propagation Delay Time (L → H) ²	t _{PLH}		T _A = 25°C	15	35	65	ns
			V _{CC} = 5 V, I _F = 7.5 mA		10		85	
Pulse Width Distortion (PWD) ²	t _{PHL} -t _{PLH}	V _{CC} = 5 V, I _F = 7.5 mA			5	35	ns	
Common Mode Transient Immunity at High Level Output ³	CM _H	V _{CC} = 5 V, T _A = 25°C, I _F = 0 mA, V _{O (MIN.)} = 2 V, V _{CM} = 100 V		1	10		kV/μs	
Common Mode Transient Immunity at Low Level Output ³	CM _L	V _{CC} = 5 V, T _A = 25°C, I _F = 7.5 mA, V _{O (MAX.)} = 0.8 V, V _{CM} = 100 V		1	10		kV/μs	

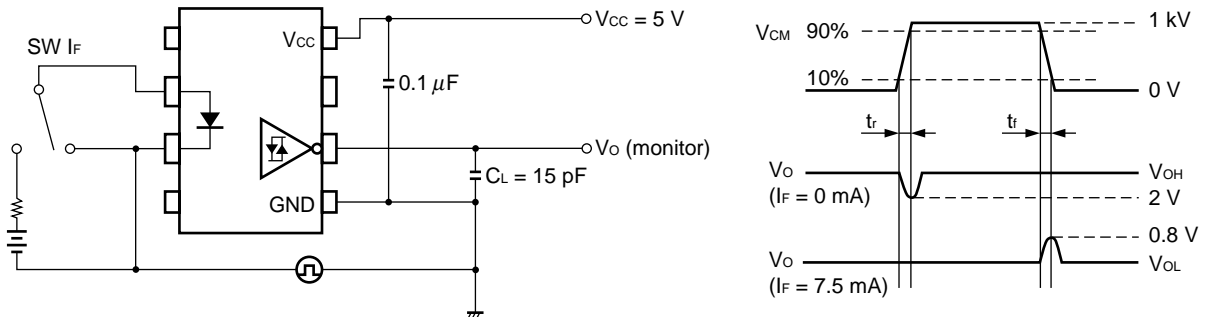
*1 Typical values at $T_A = 25^\circ\text{C}$

*2 Test circuit for propagation delay time



C_L includes probe and stray wiring capacitance.

★ *3 Test circuit for common mode transient immunity



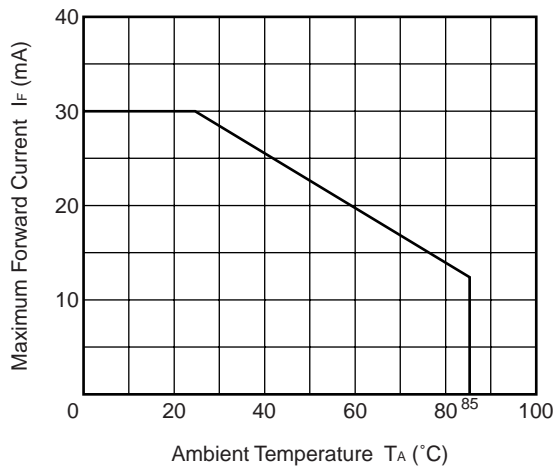
C_L includes probe and stray wiring capacitance.

USAGE CAUTIONS

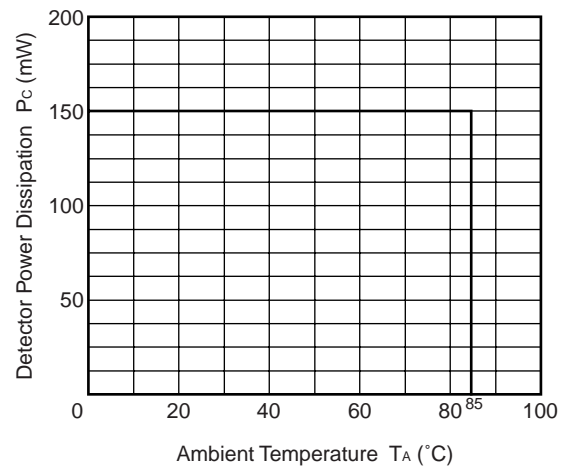
1. This product is weak for static electricity by designed with high-speed integrated circuit so protect against static electricity when handling.
2. By-pass capacitor of more than $0.1\ \mu\text{F}$ is used between V_{CC} and GND near device. Also, ensure that the distance between the leads of the photocoupler and capacitor is no more than 10 mm .

TYPICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$, unless otherwise specified)

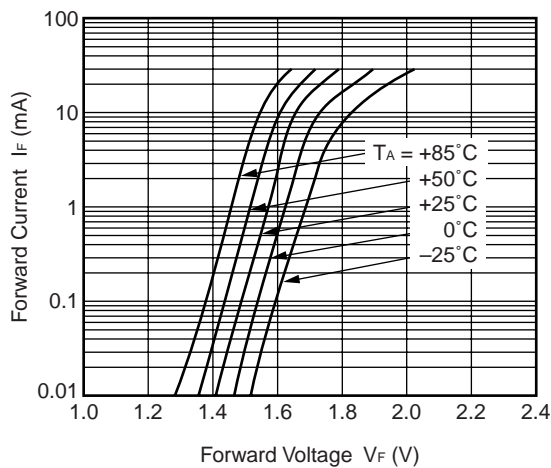
**MAXIMUM FORWARD CURRENT
vs. AMBIENT TEMPERATURE**



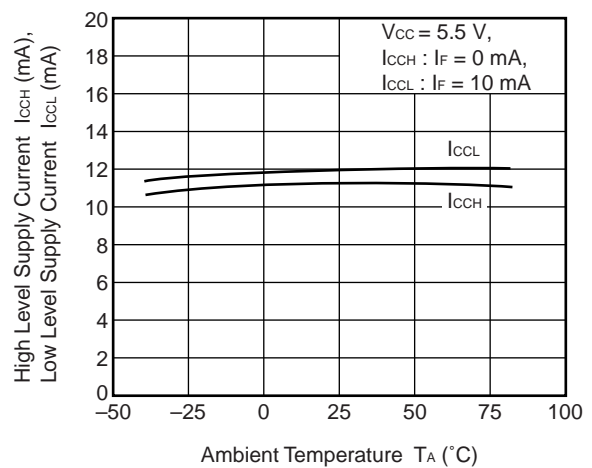
**DETECTOR POWER DISSIPATION
vs. AMBIENT TEMPERATURE**



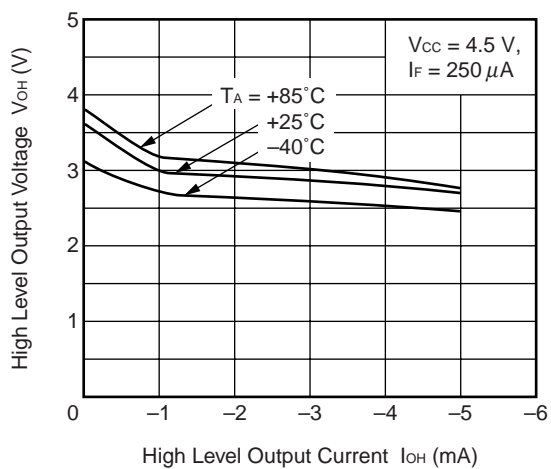
**FORWARD CURRENT vs.
FORWARD VOLTAGE**



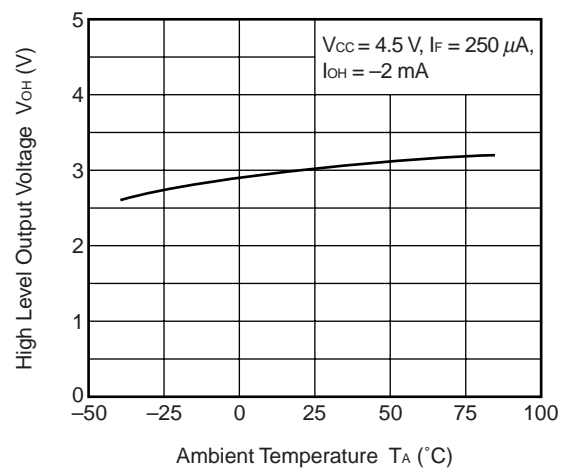
**SUPPLY CURRENT vs.
AMBIENT TEMPERATURE**



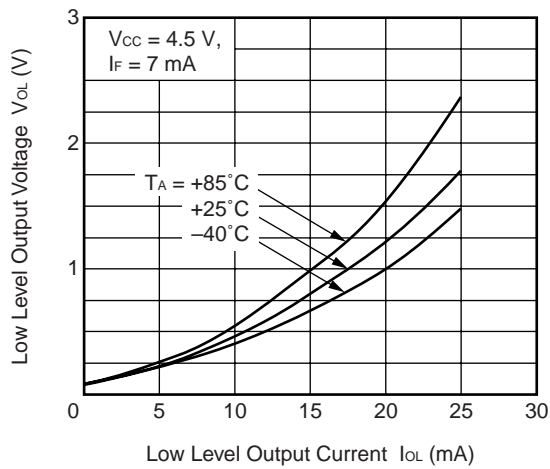
**HIGH LEVEL OUTPUT VOLTAGE vs.
HIGH LEVEL OUTPUT CURRENT**



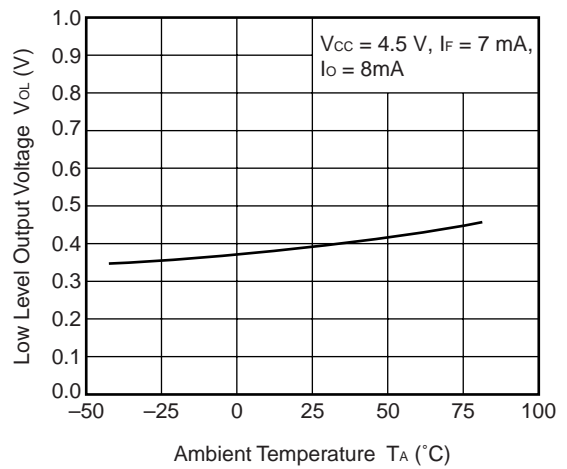
**HIGH LEVEL OUTPUT VOLTAGE vs.
AMBIENT TEMPERATURE**



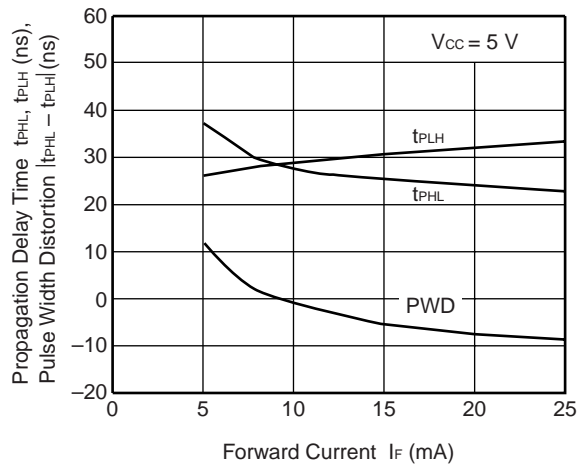
LOW LEVEL OUTPUT VOLTAGE vs.
LOW LEVEL OUTPUT CURRENT



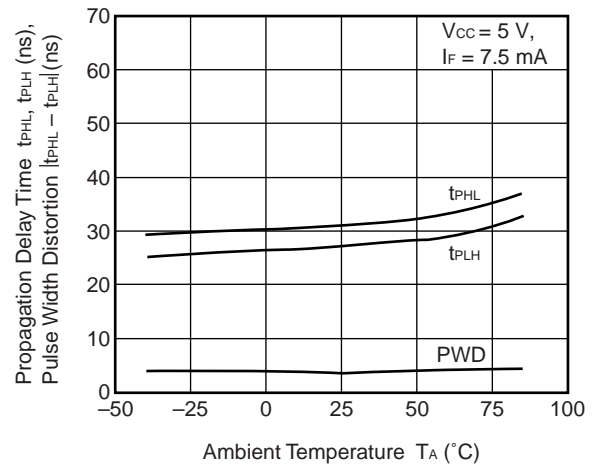
LOW LEVEL OUTPUT VOLTAGE vs.
AMBIENT TEMPERATURE



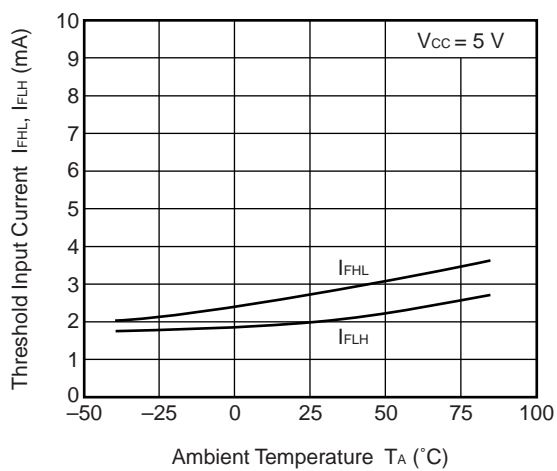
PROPAGATION DELAY TIME,
PULSE WIDTH DISTORTION
vs. FORWARD CURRENT



PROPAGATION DELAY TIME,
PULSE WIDTH DISTORTION
vs. AMBIENT TEMPERATURE



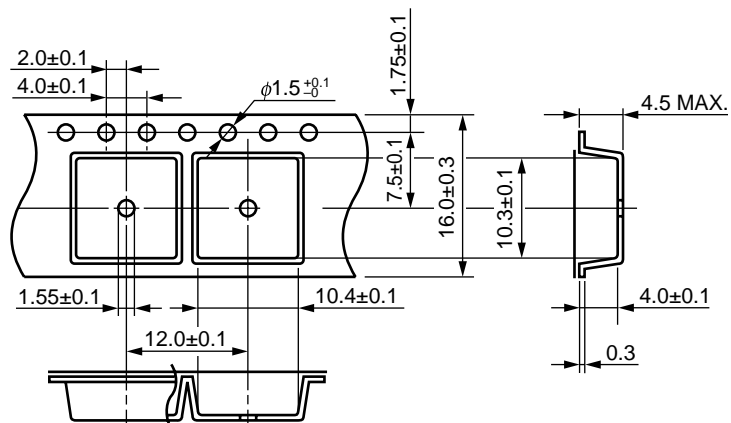
THRESHOLD INPUT CURRENT vs.
AMBIENT TEMPERATURE



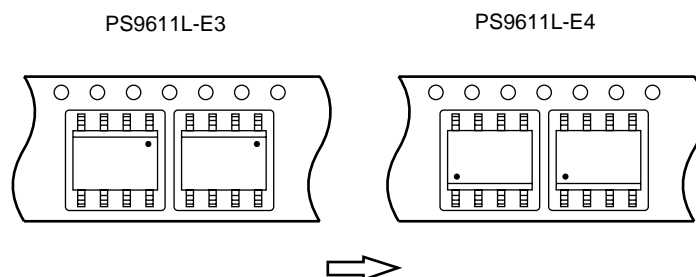
Remark The graphs indicate nominal characteristics.

★ TAPING SPECIFICATIONS (UNIT: mm)

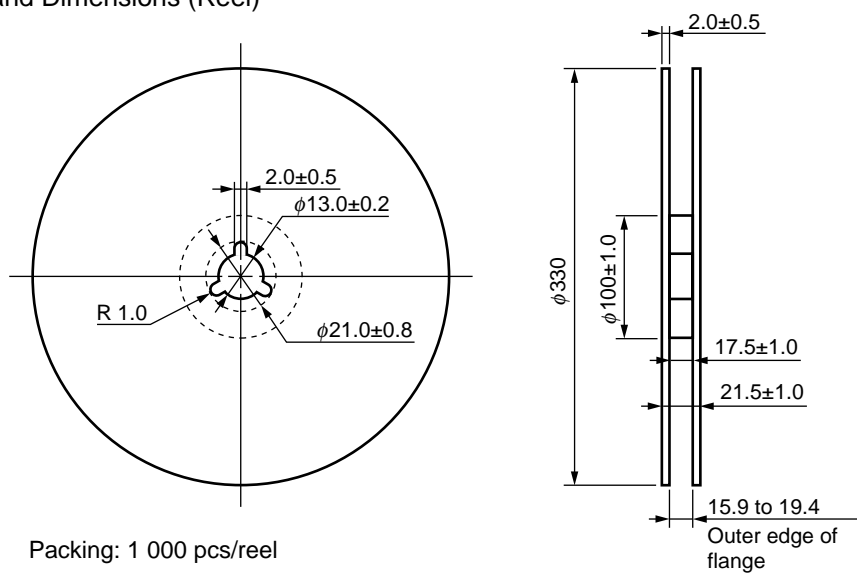
Outline and Dimensions (Tape)



Tape Direction



Outline and Dimensions (Reel)



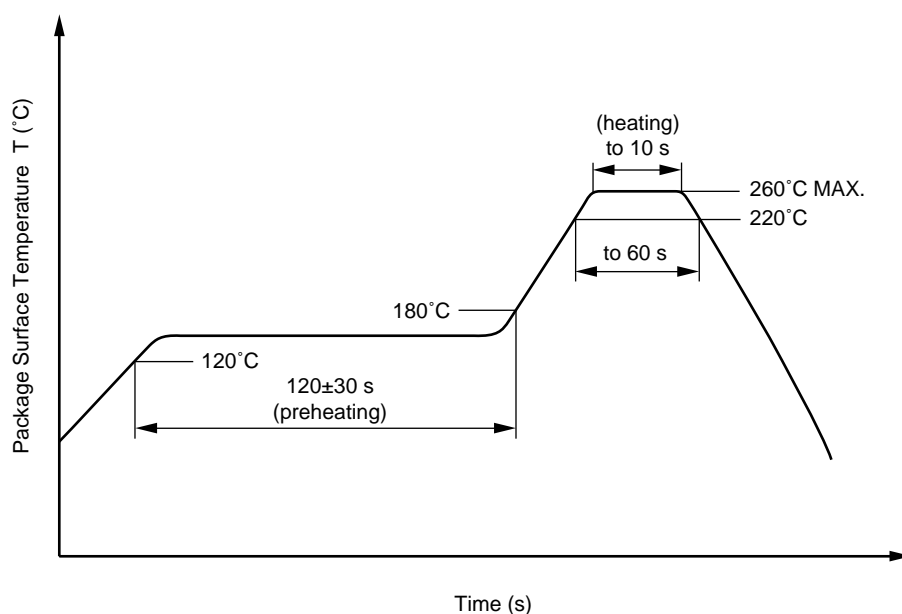
Packing: 1 000 pcs/reel

★ RECOMMENDED SOLDERING CONDITIONS

(1) Infrared reflow soldering

- Peak reflow temperature 260°C or below (package surface temperature)
- Time of peak reflow temperature 10 seconds or less
- Time of temperature higher than 220°C 60 seconds or less
- Time to preheat temperature from 120 to 180°C 120±30 s
- Number of reflows Three
- Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

Recommended Temperature Profile of Infrared Reflow



(2) Wave soldering

- Temperature 260°C or below (molten solder temperature)
- Time 10 seconds or less
- Preheating conditions 120°C or below (package surface temperature)
- Number of times One (Allowed to be dipped in solder including plastic mold portion.)
- Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

(3) Cautions

- Fluxes
 - Avoid removing the residual flux with freon-based and chlorine-based cleaning solvent.

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M8E 00.4-0110

SAFETY INFORMATION ON THIS PRODUCT

<div data-bbox="177 271 288 311" data-label="Section-Header"> <p>Caution</p> </div> <div data-bbox="300 275 448 300" data-label="Text"> <p>GaAs Products</p> </div>	<p>The product contains gallium arsenide, GaAs. GaAs vapor and powder are hazardous to human health if inhaled or ingested.</p> <ul style="list-style-type: none"> • Do not destroy or burn the product. • Do not cut or cleave off any part of the product. • Do not crush or chemically dissolve the product. • Do not put the product in the mouth. <p>Follow related laws and ordinances for disposal. The product should be excluded from general industrial waste or household garbage.</p>
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► **Business issue**

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► **Technical issue**

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